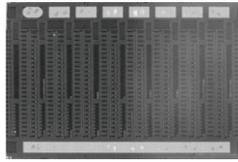
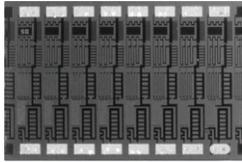




# Wire Bondable Thin Film Resistor Arrays



Product may not be to scale

The CLA and CLB resistor arrays are the hybrid equivalent to the eight resistor common connection and isolated networks available in sips or dips. The resistors are spaced on 0.010" centers resulting in minimal space requirements.

These chips are manufactured using Vishay Electro-Films (EFI) sophisticated thin film equipment and manufacturing technology. The CLA and CLBs are 100 % electrically tested and visually inspected to MIL-STD-883.

### FEATURES

- Wire bondable
- Up to 12 equal value resistors
- For case see Part Dimensions table
- Resistance range: 20 Ω to 1 MΩ
- Excellent TCR tracking
- Resistor material: tantalum nitride, self-passivating
- Oxidized silicon substrate for good power dissipation
- Custom values and pad geometries available
- Moisture resistant
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)

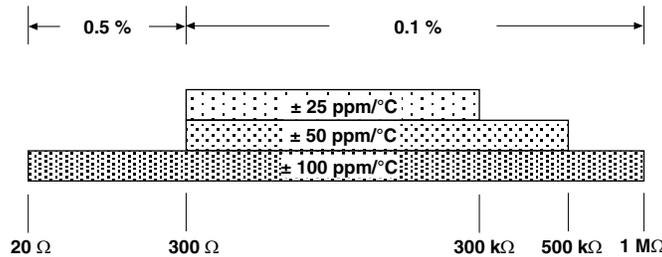


### APPLICATIONS

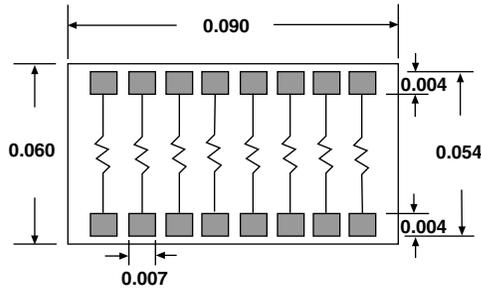
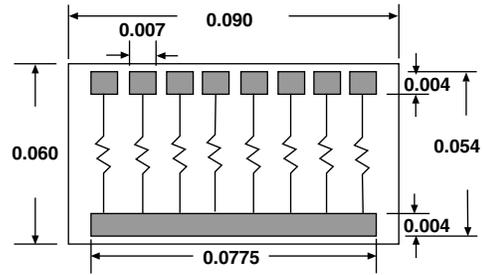
The CLA and CLB thin film resistor arrays are designed for hybrid packages requiring up to twelve resistors of the same resistance value and tolerance, as well as excellent TCR tracking. For such hybrids, they afford great savings in cost and space.

TEMPERATURE COEFFICIENT OF RESISTANCE, VALUES, AND TOLERANCES		
PARAMETER	VALUE	UNIT
Total Resistance Range	20 to 1M	Ω
Standard Tolerances	± 0.1, ± 0.5	%
TCR	± 25, ± 50, ± 100	ppm/°C

Tightest Standard Tolerance Available



STANDARD ELECTRICAL SPECIFICATIONS		
PARAMETER	VALUE	UNIT
TCR Tracking Spread	± 5	ppm/°C
Noise, MIL-STD-202, Method 308 100 Ω to 250 kΩ < 100 Ω or > 251 kΩ	-35 typ. -20 typ.	dB
Moisture Resistance, MIL-STD-202, Method 106	± 0.5 max. ΔR/R	%
Stability, 1000 h, +125 °C, 25 mW Absolute Ratio	± 0.25 max. ΔR/R ± 0.05 max. ΔR/R	%
Operating Temperature Range	-55 to +125	°C
Thermal Shock, MIL-STD-202 Method 107, Test Condition F	± 0.1 max. ΔR/R	%
High Temperature Exposure, ± 150 °C, 100 h	± 0.2 max. ΔR/R	%
Dielectric Voltage Breakdown	200	V
Insulation Resistance	10 <sup>12</sup> min.	Ω
Operating Voltage	100	V
DC Power Rating at +70 °C (Derated to Zero at 175 °C)	0.050 per resistor	W
5 x Rated Power Short-Time Overload, +25 °C, 5 s	± 0.1 % max. ΔR/R	%

**DIMENSIONS** in inches

**CLA 8 Cell**

**CLB 8 Cell**

<b>DIMENSIONS</b> in inches					
# OF RES.	03	04	06	08	12
CLA	0.060 x 0.060 ± 0.003	0.050 x 0.060 ± 0.003	0.069 x 0.060 ± 0.003	0.090 x 0.060 ± 0.003	0.130 x 0.060 ± 0.003
CLB	0.060 x 0.060 ± 0.003	0.050 x 0.060 ± 0.003	0.069 x 0.060 ± 0.003	0.090 x 0.060 ± 0.003	0.130 x 0.060 ± 0.003

<b>MECHANICAL SPECIFICATIONS</b>	
PARAMETER	
Chip Size	See Dimensions table above
Chip Thickness	0.010" ± 0.002" (0.254 mm ± 0.05 mm)
Chip Substrate Material	Oxidized silicon, 10 kÅ minimum SiO <sub>2</sub>
Resistor Material	Tantalum nitride, self-passivating
Bonding Pads	0.004" x 0.007" (0.10 mm x 0.178 mm)
Number of Top Pads	CLA - 16 CLB - 9
Pad Material	10 kÅ minimum aluminum
Backing	None, lapped semiconductor silicon

<b>GLOBAL PART NUMBER INFORMATION</b>												
Global Part Number: CLA083000FFKANHWS												
Global Part Number Description: CLA 8 Res 3K 1%, 100 ppm/°C, Al terminations, no back metal, class H WS												
<div style="display: flex; justify-content: space-around; font-weight: bold; font-size: 1.2em;"> <span>C</span><span>L</span><span>A</span><span>0</span><span>8</span><span>3</span><span>0</span><span>0</span><span>0</span><span>0</span><span>F</span><span>F</span><span>K</span><span>A</span><span>N</span><span>H</span><span>W</span><span>S</span> </div>												
MODEL	TYPE	RESISTORS	RES.	RES. MULTIPLIER CODE	TOL. CODE	RATIO TOL.	TCR (ppm/°C)	TERM.	BACK METAL	VISUAL CLASS	PACKAGING CODE	
CL	A = isolated B = bussed	03 04 05 06 07 08 09 10 11 12	First 4 digits are significant figures of resistance	B = 0.01 A = 0.1 0 = 1 1 = 10 2 = 100 3 = 1000	B = 0.1 % C = 0.25 % D = 0.5 % F = 1.0 % G = 2.0 % J = 5.0 % K = 10.0 %	B = 0.1 % F = 1.0 % N = none	E = ± 25 C = ± 50 K = ± 100 M = ± 250	G = Au A = Al	G = Au N = none	H = class H K = class K	WS = waffle pack, 100 min., 1 mult.	



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